

PCN Number: CO-22064	O-22064 Contact: Elizabeth La Greca			
Date Issued: November 13th, 2018	Title: Director, Sales Operations			
PCN Effective Date: February 13th, 2019	Phone: 1-858-795-0106			
Product(s) Affected: PE42553	Email: pcn@psemi.com			
Sample Availability: November 13th, 2018				
Change Control Board Approval #: CO-22064				
Change Category:				
	☐ Shipping/Labeling			
☐ Design/Mask Change	☐ Equipment			
☐ Singulation Process	☐ Material			
Assembly Process	☐ Product Specification			
☐ Electrical Test	Product End of Life			
☐ Manufacturing Site	Other - Ordering codes change			
Purpose of Change:				
To enable Lapis as the primary wafer fabrication site	for the PE42553.			
Description of Change:				
MagnaChip closed their 150 mm wafer CMOS fab in South Korea at the end of 2015. To ensure there is no disruption to supply, we have been working to transfer products from MagnaChip fab to Lapis fab in Japan. Magnachip and Lapis are qualified pSemi fabs.				
Lapis PE42553 material has been qualified with no cl	hange to form, fit, function or reliability			
Beginning <u>February 13th, 2019</u> , the PE42553 shipped to customers will be supplied from either MagnaChip or Lapis wafers. Lapis will become the primary wafer fabrication site for the PE42553.				
Ordering code changes:				
Ordering code changes:				
Ordering code changes: Original ordering codes (MagnaChip): PE42553A-Z; E	EK42553-01			
Original ordering codes (MagnaChip): PE42553A-Z; E				



Customer Acknowledgement of Receipt:			
Change Denied	Name:		
(Include explanation in comments section below)	Title:		
☐ Change Approved	Company:		
	Date:		
	Signature:		
Customer Comments:			



Appendix A - Reliability Qualification Summary



PE42553

Reliability Summary Report

Part Number(s):	PE42553	Product Family:	RF Switch	
Package Type:	16L 3x3 QFN	MSL Rating:	MSL 3	
Technology Platform:	ULTRACMOS®5			
Reliability Summary:	Based on the results of reliability testing, the PE42553 has met the reliability requirements for Production.			

Table 1: Product Design Reliability Results

Test #	Test Performed	TEST METHOD/ Conditions	Duration	Sample Size	Result
1	High Temperature Operating Life (HTOL)	Mil-Std-883 M1005.9/ JESD22-A108 VDD= 5.5V; VCTL= 3.6V; TA = TJ= 150°C;	500 hrs.	1 lot x 77	Pass
2	ESD 2 Human Body Model (HBM)	Mil-Std-883 M3015 (All pins)	2.5kV	1 lot x 3	Pass
2		Mil-Std-883 M3015 (RF Pins Only)	4kV	1 lot x 3	Pass
3	ESD Machine Model (MM)	JEDEC JESD22-A115	200V	1 lot x 3	Pass
4	ESD Charged Device Model (CDM)	JEDEC JESD22-C101	1000V	1 lot x 3	Pass

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Reliability Summary Report

Table 2: Package Reliability Results

Test #	Test Performed	TEST METHOD/ Conditions	Duration	Sample Size	Result
5	HTOL	Mil-Std-883 M1005.9/ JESD22-A108	500 hrs.	1 lot x 77	Pass
6	HTS	Mil-Std-883 M1008.2/ JESD22-A103 T _A = 150°C	1,000 hrs.	1 lot x 77	Pass
7	HAST	JESD22-A110 VDD= 3.3 V; VCTL= 3.3V; P _v = 2.270 atm;	96 hrs.	3 lots x 45	Pass
8	TC	Mil-Std-883 M1010.8/ JESD22-A104	500 cycs.	3 lots x 45	Pass
9	TS	JESD22-A105 T _A = -55°C to +125°C	100 cycs.	3 lots x 45	Pass
10	WBP	Mil-Std-883 M2011.8/ JESD22-B115	-	3 lots x 20	Pass
11	Physical Dimensions	Mil-Std-883 M2016/ JESD22-B100	-	3 lots x 10	Pass
12	Die Shear	Mil-Std-883 M2019.8	-	3 lots x 5	Pass
13	Solderability	Mil-Std-883 M2003.9/ JESD22-B102	-	3 lots x 10	Pass

Technology Reliability Report (DOC-81028)